

RoHS Compliance Material Declaration Report

| Company: | Pericom |
|----------|------------------|
| Name: | Nang Su |
| Title: | Quality Engineer |
| e-mail: | nsu@pericom.com |

| Address: | 3545 North First Street, San Jose, CA, 95134 |
|---------------|--|
| Phone number: | (408) 435 0800 |
| Date: | 3/14/2007 |

| Part Detail | | | | | | |
|---------------------|--|-------------------------------|---------------------|------------------------|--------------------------|--|
| Pericom Part Number | | Manufacturer part description | Package Type | Number of Pin/Terminal | Component overall weight | |
| PI90LVT386AE | | 16 LVDS Receivers | TSSOP (6.1mm width) | 64 | 0.263851 | |

| RoHS Compliance | | | | |
|---|----------------------------------|--|--|--|
| Is Part compliant to EU RoHS Directive? [1] Yes, [2] Yes with tech exemption* [3] Yes but needs product application exemption* [4] No | RoHS tech exemption [2] details. | Date Component was RoHS Compliant. | | |
| Yes | N/A | Since Inception | | |

| Content of RoHS restricted materials (g) | | | | | | |
|--|---------|---------|------------------------|--------------------------------|--|---|
| Lead | Cadmium | Mercury | Hexavalent Chromium | Polybrominated biphenyls (PBB) | Polybrominated Diphenylethers (PBDE) | RoHS restricted substance added intentionally? For what reason? |
| 0 | 0 | 0 | 0 | 0 | 0 | N/A |

| Component Soldering Process | | | | | | |
|---|----------------------------------|---|--|--|-----------------------------|-----------------------------|
| Interconnect Composition, (Metallurgy of the lead/terminal) | JEDEC JEDS97 Pb-free Category | Compatible with a 260C 10s Pb-Free assembly process | Backward compatible with SnPb assembly | Maximum Processing Temperature (°C) | Max Temperature Duration | Max Number of reflow cycles |
| Sn | e3 | Yes | Yes | 260 | 40 | 3 |

| Plastics (if applicable) | | | | |
|---|-------------|-----------------|-----------------------------------|--|
| Oxygen Index Type of plastic material used in the component | | Fire: UL Rating | MSL Level (per JEDEC STD 020C) | |
| >28% | Epoxy Resin | V-0 | 1 | |

| Tin (Sn) Plating (If Applicable) | | | | | | |
|--|-------------------------------|---|-----------------------------|---|---------------------------------|--|
| Tin (Sn) Plating – is it Matte (M) or Bright (B)? | Tin (Sn) Plating Thickness | Tin (Sn) plating is there a Nickel (Ni) Barrier? - Yes / No | Nickel Barrier Thickness | If no Nickel barrier is the tin (Sn) termination finish heat treated? | Performed Tin Whisker Test ? | |
| М | 7 to 20 um | No | N/A | Yes, 150C / 1 Hr | Yes | |

| Bismuth (Bi) | | |
|--------------------------------------|---|--|
| Bismuth (Bi) Content (if applicable) | | |
| | | |
| | 0 | |

Document Name: RoHS MDR

Revision: A Sheet 1 of 1